



SPECIFICATION

• Supplier : Samsung electro-mechanics • Samsung P/N : CL31B223KCCNNNC

• Product : Multi-layer Ceramic Capacitor • Description : CAP, 22nF, 100V, ±10%, X7R, 1206

A. Samsung Part Number

<u>CL</u> <u>31</u> <u>B</u> <u>223</u> <u>K</u> <u>C</u> <u>C</u> <u>N</u> <u>N</u> <u>N</u> <u>C</u> ① ② ③ ④ ⑤ ⑥ ⑦ ⑧ ⑨ ⑩ ⑪

① S	Series	Samsung Multi-layer Ceramic Capacitor								
② S	Size	1206	(inch code)	L: 3.2	± 0.15	mm	W:	1.6	± 0.15	mm
3 D	Dielectric	X7R		8	Inner el	ectrode		Ni		
4 C	apacitance	22	nF		Termina	ation		Cu		
⑤ C	apacitance	±10	%		Plating			Sn 10	0%	(Pb Free)
to	olerance			9	Product	t		Norma	al	
6 R	Rated Voltage	100	V	10	Special			Reserved for future use		
⑦ T	hickness	0.85	± 0.15 mm	11)	Packaging			Cardboard Type, 7" reel		

B. Samsung Reliablility Test and Judgement condition

	Performance	Test condition					
Capacitance	Within specified tolerance	1klb±10% 1.0±0.2Vrms					
Tan δ (DF)	0.025 max.						
Insulation	10,000Mohm or 500Mohm·μF	Rated Voltage 60~120 sec.					
Resistance	Whichever is Smaller						
Appearance	No abnormal exterior appearance	Microscope (×10)					
Withstanding	No dielectric breakdown or	200% of the rated voltage					
Voltage	mechanical breakdown						
Temperature	X7R						
Characterisitcs	(From -55 $^{\circ}\!$						
Adhesive Strength	No peeling shall be occur on the	500g·F, for 10±1 sec.					
of Termination	terminal electrode						
Bending Strength	Capacitance change: within ±12.5%	Bending to the limit (1mm)					
		with 1.0mm/sec.					
Solderability	More than 75% of terminal surface	SnAg3.0Cu0.5 solder					
	is to be soldered newly	245±5℃, 3±0.3sec.					
		(preheating : 80~120℃ for 10~30sec.)					
Resistance to	Capacitance change: within ±7.5%	Solder pot : 270±5℃, 10±1sec.					
Soldering heat	Tan δ, IR : initial spec.						

	Performance	Test condition
Vibration Test	Capacitance change : within ±5%	Amplitude : 1.5mm
	Tan δ, IR : initial spec.	From 10Hz to 55Hz (return : 1min.)
		2hours × 3 direction (x, y, z)
Moisture	Capacitance change : within ±12.5%	With rated voltage
Resistance	Tan δ : 0.05 max	40±2℃, 90~95%RH, 500+12/-0hrs
	IR : 500Mohm or 25Mohm ⋅ μF	
	Whichever is Smaller	
High Temperature	Capacitance change : within ±12.5%	With 200% of the rated voltage
Resistance	Tan δ : 0.05 max	Max. operating temperature
	IR : 1000Mohm or 50Mohm · μF	
	Whichever is Smaller	1000+48/-0hrs
Temperature	Capacitance change : within ±7.5%	1 cycle condition
Cycling	Tan δ, IR : initial spec.	Min. operating temperatur → 25 °C
		→ Max. operating temperature → 25°C
		5 cycle test

C. Recommended Soldering method :

Reflow (Reflow Peak Temperature : 260+0/-5 $^{\circ}$ C, 10sec. Max)

^{*} For the more detail Specification, Please refer to the Samsung MLCC catalogue.